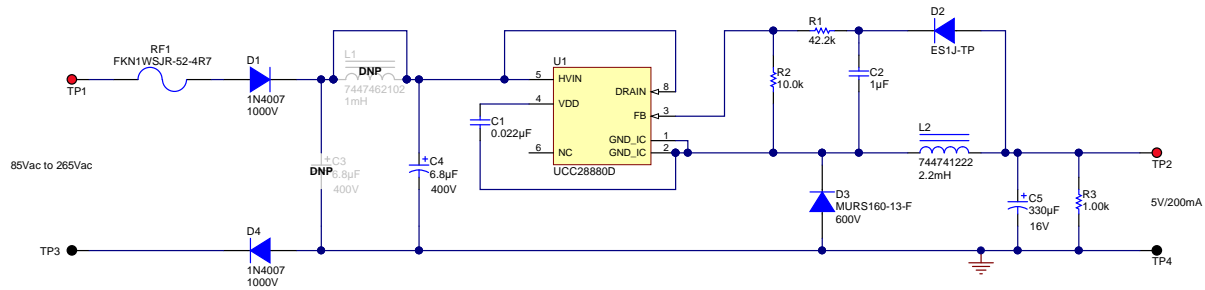


Note: Inductor with lower DCR is recommended for L2.



Built on PMP9073Rev A PCB.

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Number: PMP20834	Rev: A	Designed for Public Release	Mod. Date: 3/23/2017
SVN Rev: Version control disabled	Assembly Variant: 001	Project Title: UCC28881 High-side Buck Converter	Sheet Title: 85Vac-265Vac to 5V/0.2A
Drawn By: S Yu	File: PMP9073_01.SchDoc	Sheet: 1 of 2	Size: B
Engineer: Sheng-Yang Yu	Contact: http://www.ti.com/support		



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